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Dated: April 16, 2002

Signature: M.J. Doherty
(Michael J. Doherty)

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Docket No.: TESSERA 3.0-078 DIV

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

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PATENT & TRADE
re Patent Application of:
Fjelstad et al.

Application No.: 09/020,647

Filed: February 9, 1998

For: METHODS OF MAKING COMPLIANT
SEMICONDUCTOR CHIP PACKAGES
(As Amended)

Group Art Unit: 2814

Examiner: D. Graybill

#31/E
P. Evans
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AMENDMENT

Commissioner for Patents
Washington, DC 20231

Dear Sir:

In response to the Office Action dated December 7, 2001, rejecting claims 35-57, please amend the above-identified U.S. Patent application as follows:

In the Claims

36. (Amended) The method according to Claim 35, further comprising after selectively electroplating said bond ribbons, providing a second dielectric protective layer over exposed elements on the terminal side of said package, wherein said second dielectric protective layer has a plurality of apertures extending therethrough for providing access to said terminals.

37. (Amended) The method according to Claim 35, wherein said compliant layer comprises a material selected from the group consisting of silicone, flexibilized epoxy, a